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 In case of consideration for using Automotive equipment / device which demand high reliability, kindly contact our sales window correspondents.

SPECIFICATIONS					
ITEM	TEST METHOD	REQUIREMENTS	QT	AT	
RESISTANCE TO SOLDERING HEAT	1) AUTOMATIC SOLDERING (REFLOW) 《REFLOW AREA》 MAX 250°C WITHIN 10 sec. MIN 230°C WITHIN 60 sec. 《PREHEATING AREA》 150 TO 180°C 90 TO 120 sec. PUT THROUGH IN REFLOW FURNACE TWICE. LEAVE IN AMBIENT TEMPERATURE AND HUMIDITY FOR 1 HOUR. CONNECTOR TEMPERATURE TO BE AMBIENT FOR SECOND REFLOW. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE :290±10°C, SOLDERING TIME :3s. NO STRENGTH ON CONTACT.	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.	X	—	
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE, 230±5°C FOR IN IMMERSION , DURATION, 3 s.	A NEW UNIFORM COATING OF SOLDER SHALL COVER MINIMUM OF 95 % OF THE SURFACE BEING IMMersed.	X	—	
REMARKS NOTE 1:INCLUDING THE TEMPERATURE RISE BY CURRENT. NOTE 2:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD , AFTER PCB BOARD , OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERM STORAGE DURING TRANSPORTATION. NOTE 3:THE TEMPERATURE PROFILE SHALL BE APPLIED WITHIN 168 HOURS AFTER OPENING MOISTURE-PROOF PACKAGING. WHEN 168 HOURS PASSED AFTER OPENING , APPLY THE BOTTOM REQUIREMENTS. 《REFLOW AREA》 MAX 240°C WITHIN 10 sec. MIN 230°C WITHIN 60 sec. 《PREHEATING AREA》 150 TO 180°C 90 TO 120 s.					
Unless otherwise specified , refer to IEC 60512 					
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC4-163554-05
	SPECIFICATION SHEET		PART NO.	DF11C-*DP-2V (57)	
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